

### Mini Top View LEDs EAPL2214GA1

PRELIMINARY



#### Features

- White SMT package.
- Optical indicator.
- Wide viewing angle.
- Soldering methods: reflow soldering
- Available on tape and reel
- Pb-free
- The product itself will remain within RoHS compliant version.

#### Applications

- Optical indicators.
- Coupling into light guides.
- Backlighting (LCD, cellular phones, switches, keys, displays, illuminated advertising, general lighting).
- Coupling into light guides; Interior automotive lighting (e.g. dashboard backlighting, etc.).

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Brilliant Green	Water Clear

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	25	mA
Power Dissipation	$P_d$	100	mW
Peak Forward Current (Duty 1/10 @1KHz)	$I_{FP}$	95	mA
Electrostatic Discharge(HBM)	ESD	150	V
Operating Temperature	$T_{opr}$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40~ +90	°C
Soldering Temperature	$T_{sol}$	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	225	-----	565	mcd	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>	----	120	----	deg	
Peak Wavelength	λ <sub>p</sub>	----	518	----	nm	
Dominant Wavelength	λ <sub>d</sub>	520	----	535	nm	
Spectrum Radiation Bandwidth	Δλ	----	20	----	nm	
Forward Voltage	V <sub>F</sub>	2.70	----	3.70	V	
Reverse Current	I <sub>R</sub>	----	----	50	μA	VR=5V

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

### Bin Range of Luminous Intensity

Bin	Min	Max	Unit	Condition
S2	225	285	mcd	I <sub>F</sub> =20mA
T1	285	360		
T2	360	450		
U1	450	565		

Note: Tolerance of Luminous Intensity: ±11%

### Bin Range of Dominant Wavelength

Group	Bin	Min	Max	Unit	Condition
Y	X	520	525	nm	I <sub>F</sub> =20mA
	Y	525	530		
	Z	530	535		

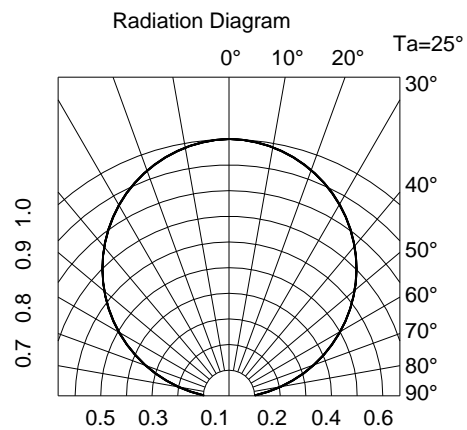
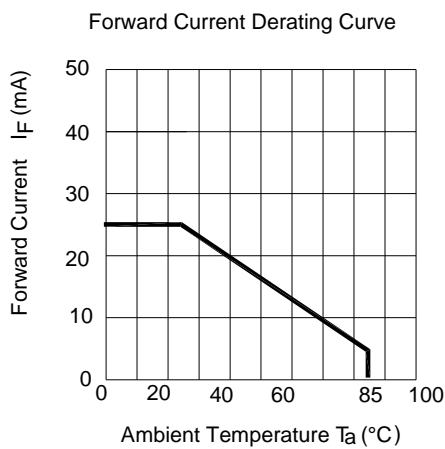
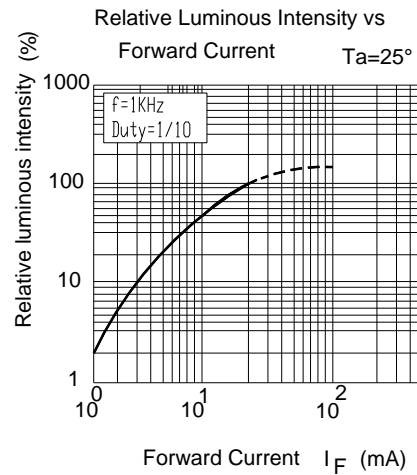
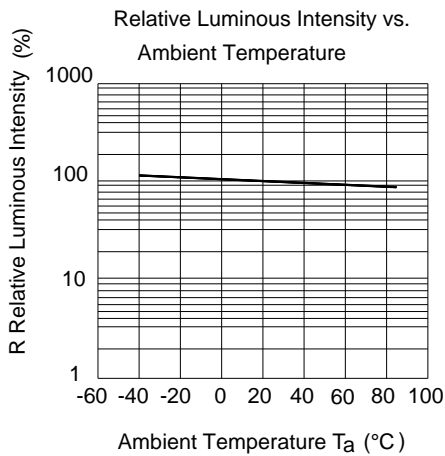
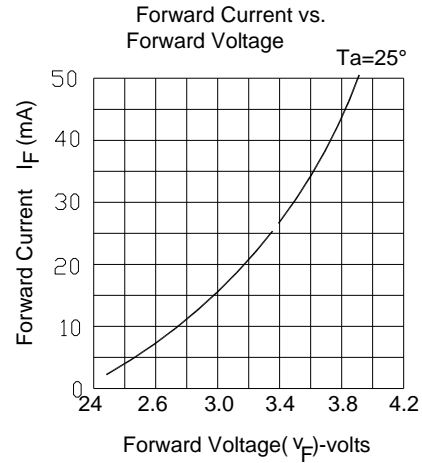
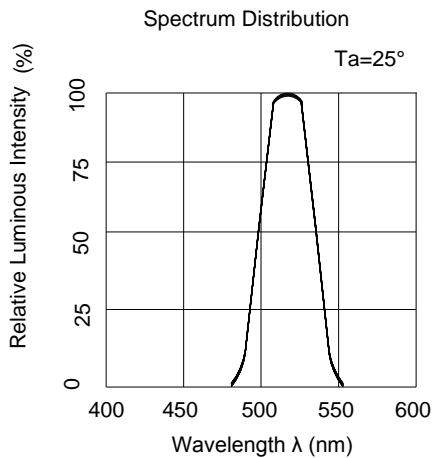
Note: Tolerance of Dominant Wavelength: ±1nm

**Bin Rang of Forward Voltage**

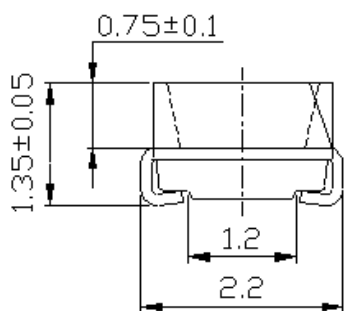
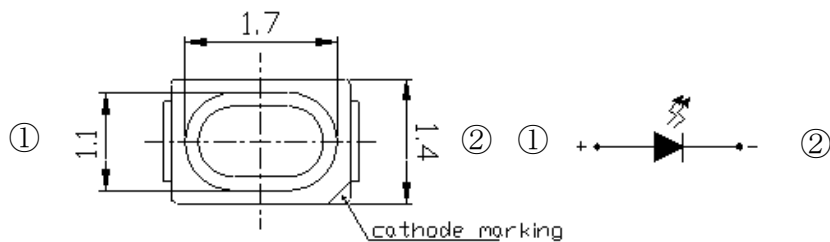
Group	Bin	Min	Max	Unit	Condition
G	34	2.70	2.80	V	I <sub>F</sub> =20mA
	35	2.80	2.90		
	36	2.90	3.00		
	37	3.00	3.10		
	38	3.10	3.20		
	39	3.20	3.30		
	40	3.30	3.40		
	41	3.40	3.50		
	42	3.50	3.60		
	43	3.60	3.70		

Note: Tolerance of Forward Voltage ±0.1V

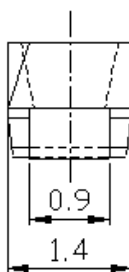
### Typical Electro-Optical Characteristics Curves



### Package Dimension



Polarity



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

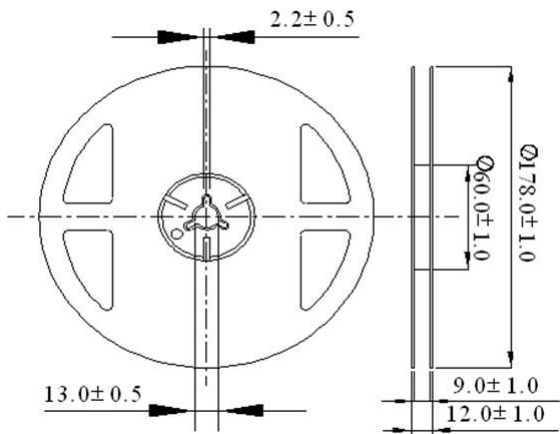
## Moisture Resistant Packing Materials

### Label Explanation

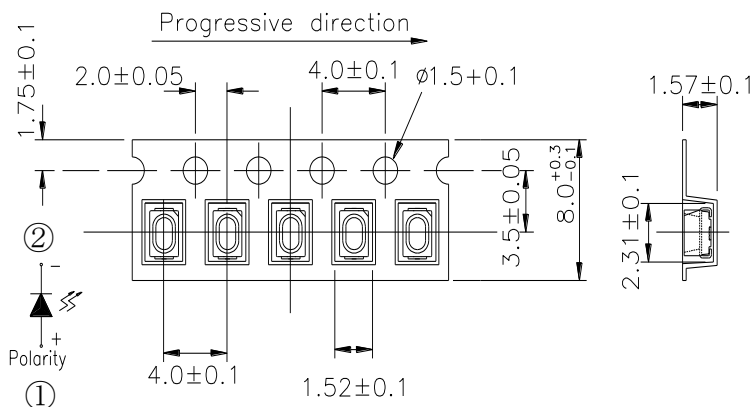


- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

### Reel Dimensions

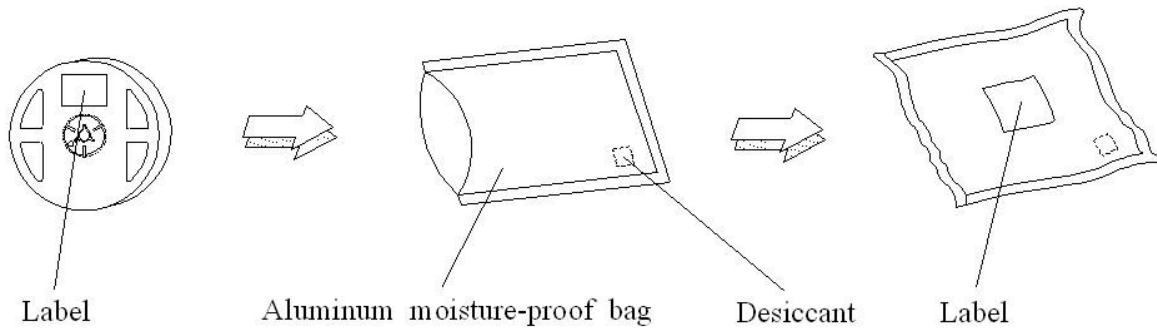


### Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

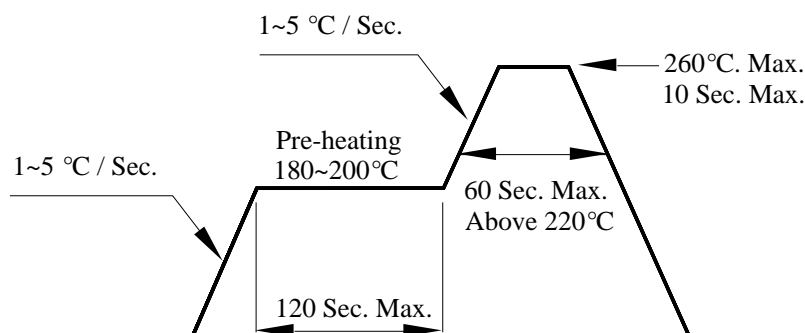
### Moisture Resistant Packing Process



Note: Tolerances unless mentioned  $\pm 0.1\text{mm}$ . Unit = mm

### Precautions for Use

1. Over-current-proof  
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package, the LEDs should be kept at  $30^{\circ}\text{C}$  or less and 90%RH or less.
  - 2.3 After opening the package: The LED's floor life are 168 hours under  $30^{\circ}\text{C}$  or less and 60% RH or less.  
If unused LEDs remain, it should be stored in moisture proof packages.
  - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.  
Baking treatment :  $60\pm 5^{\circ}\text{C}$  for 24 hours.
3. Soldering Condition
  - 3.1 Pb-free solder temperature profile
  - 3.2 Reflow soldering should not be done more than two times.
  - 3.3 When soldering, do not put stress on the LEDs during heating.
  - 3.4 After soldering, do not warp the circuit board.





#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 280°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

